

XC7SET14

Inverting Schmitt trigger

Rev. 01 — 31 August 2009

Product data sheet

1. General description

XC7SET14 is a high-speed Si-gate CMOS device. It provides an inverting buffer function with Schmitt trigger action. This device is capable of transforming slowly changing input signals into sharply defined, jitter-free output signals.

2. Features

- Symmetrical output impedance
- High noise immunity
- ESD protection:
 - ◆ HBM JESD22-A114E: exceeds 2000 V
 - ◆ MM JESD22-A115-A: exceeds 200 V
 - ◆ CDM JESD22-C101C: exceeds 1000 V
- Low power dissipation
- Balanced propagation delays
- SOT353-1 and SOT753 package options
- Specified from -40 °C to +125 °C

3. Applications

- Wave and pulse shapers
- Astable multivibrators
- Monostable multivibrators

4. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
XC7SET14GW	-40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
XC7SET14GV	-40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753

5. Marking

Table 2. Marking codes

Type number	Marking code ^[1]
XC7SET14GW	gF
XC7SET14GV	g14

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

6. Functional diagram

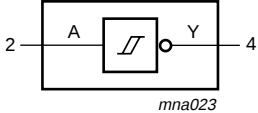


Fig 1. Logic symbol

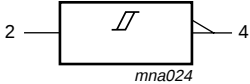


Fig 2. IEC logic symbol

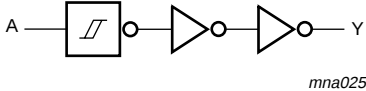


Fig 3. Logic diagram

7. Pinning information

7.1 Pinning

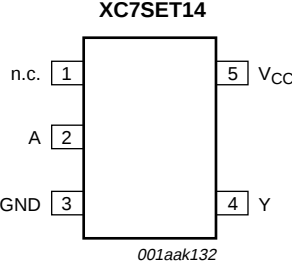


Fig 4. Pin configuration SOT353-1 and SOT753

7.2 Pin description

Table 3. Pin description

Symbol	Pin	Description
n.c.	1	not connected
A	2	data input
GND	3	ground (0 V)
Y	4	data output
V _{CC}	5	supply voltage

8. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level

Input	Output
A	Y
L	H
H	L

9. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+7.0	V
V_I	input voltage		-0.5	+7.0	V
I_{IK}	input clamping current	$V_I < -0.5\text{ V}$	-20	-	mA
I_{OK}	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	[1] -	±20	mA
I_O	output current	$-0.5\text{ V} < V_O < V_{CC} + 0.5\text{ V}$	-	±25	mA
I_{CC}	supply current		-	75	mA
I_{GND}	ground current		-75	-	mA
T_{stg}	storage temperature		-65	+150	°C
P_{tot}	total power dissipation	$T_{amb} = -40\text{ °C}$ to $+125\text{ °C}$	[2] -	250	mW

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For both TSSOP5 and SC-74A packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

10. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CC}	supply voltage		4.5	5.0	5.5	V
V_I	input voltage		0	-	5.5	V
V_O	output voltage		0	-	V_{CC}	V
T_{amb}	ambient temperature		-40	+25	+125	°C

11. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V _{OH}	HIGH-level output voltage	V _I = V _{T+} or V _{T–} ; V _{CC} = 4.5 V								
		I _O = –50 µA	4.4	4.5	-	4.4	-	4.4	-	V
		I _O = –8.0 mA	3.94	-	-	3.8	-	3.70	-	V
V _{OL}	LOW-level output voltage	V _I = V _{T+} or V _{T–} ; V _{CC} = 4.5 V								
		I _O = 50 µA	-	0	0.1	-	0.1	-	0.1	V
		I _O = 8.0 mA	-	-	0.36	-	0.44	-	0.55	V
I _I	input leakage current	V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V	-	-	0.1	-	1.0	-	2.0	µA
I _{CC}	supply current	V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	1.0	-	10	-	40	µA
ΔI _{CC}	additional supply current	per input pin; V _I = 3.4 V; other inputs at V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V	-	-	1.35	-	1.5	-	1.5	mA
C _I	input capacitance		-	1.5	10	-	10	-	10	pF

11.1 Transfer characteristics

Table 8. Transfer characteristics

At recommended operating conditions; voltages are referenced to GND (ground = 0 V). See [Figure 7](#) and [Figure 8](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
V _{T+}	positive-going threshold voltage	V _{CC} = 4.5 V	-	-	2.0	-	2.0	-	2.0	V
		V _{CC} = 5.5 V	-	-	2.0	-	2.0	-	2.0	V
V _{T–}	negative-going threshold voltage	V _{CC} = 4.5 V	0.5	-	-	0.5	-	0.5	-	V
		V _{CC} = 5.5 V	0.6	-	-	0.6	-	0.6	-	V
V _H	hysteresis voltage	V _{CC} = 4.5 V	0.4	-	1.4	0.4	1.4	0.35	1.4	V
		V _{CC} = 5.5 V	0.4	-	1.6	0.4	1.6	0.35	1.6	V

12. Dynamic characteristics

Table 9. Dynamic characteristics

GND = 0 V. For waveform see [Figure 5](#). For test circuit see [Figure 6](#).

Symbol	Parameter	Conditions	25 °C			–40 °C to +85 °C		–40 °C to +125 °C		Unit
			Min	Typ	Max	Min	Max	Min	Max	
t _{pd}	propagation delay	A to Y; [1]								
		V _{CC} = 4.5 V to 5.5 V [2]								
		C _L = 15 pF	-	4.1	7.0	1.0	8.0	1.0	9.0	ns
		C _L = 50 pF	-	5.9	8.5	1.0	10.0	1.0	11.0	ns
C _{PD}	power dissipation capacitance	per buffer; [3] V _I = GND to V _{CC}	-	13	-	-	-	-	-	pF

[1] t_{pd} is the same as t_{PLH} and t_{PHL}.

[2] Typical values are measured at V_{CC} = 5.0 V.

[3] C_{PD} is used to determine the dynamic power dissipation P_D (μW).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:

f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in V.

13. Waveforms

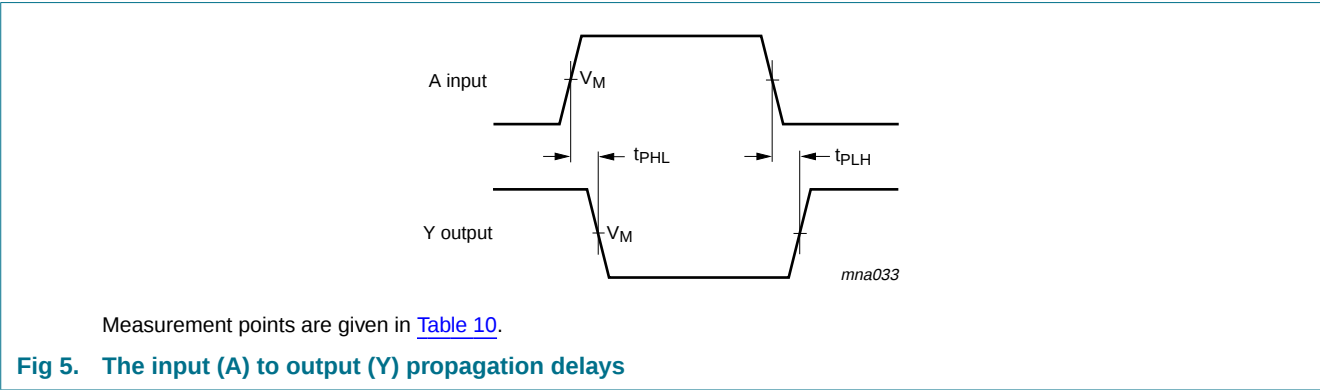


Table 10. Measurement points

Type number	Input		Output
	VI	VM	VM
XC7SET14	GND to 3.0 V	1.5 V	0.5 × VCC

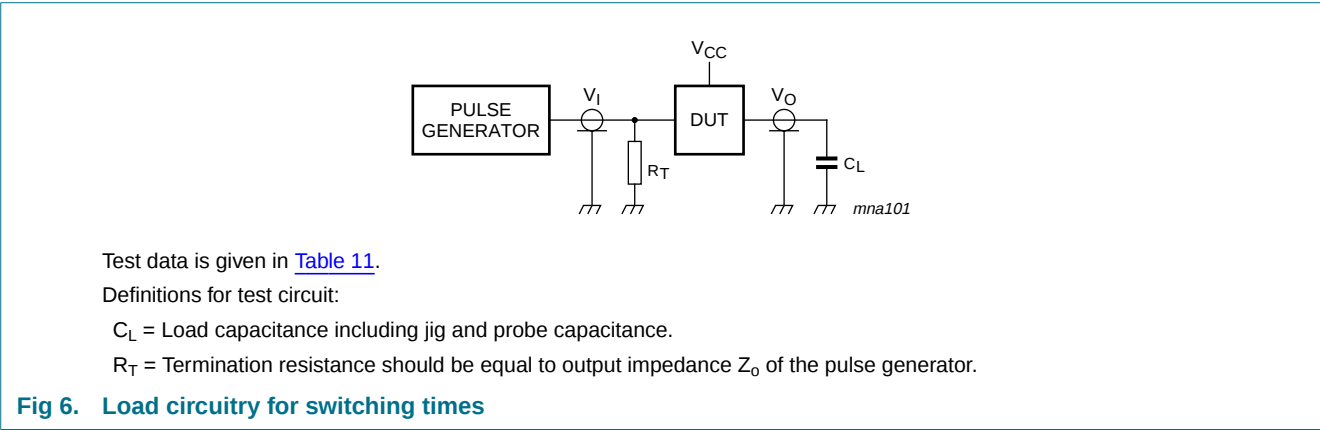
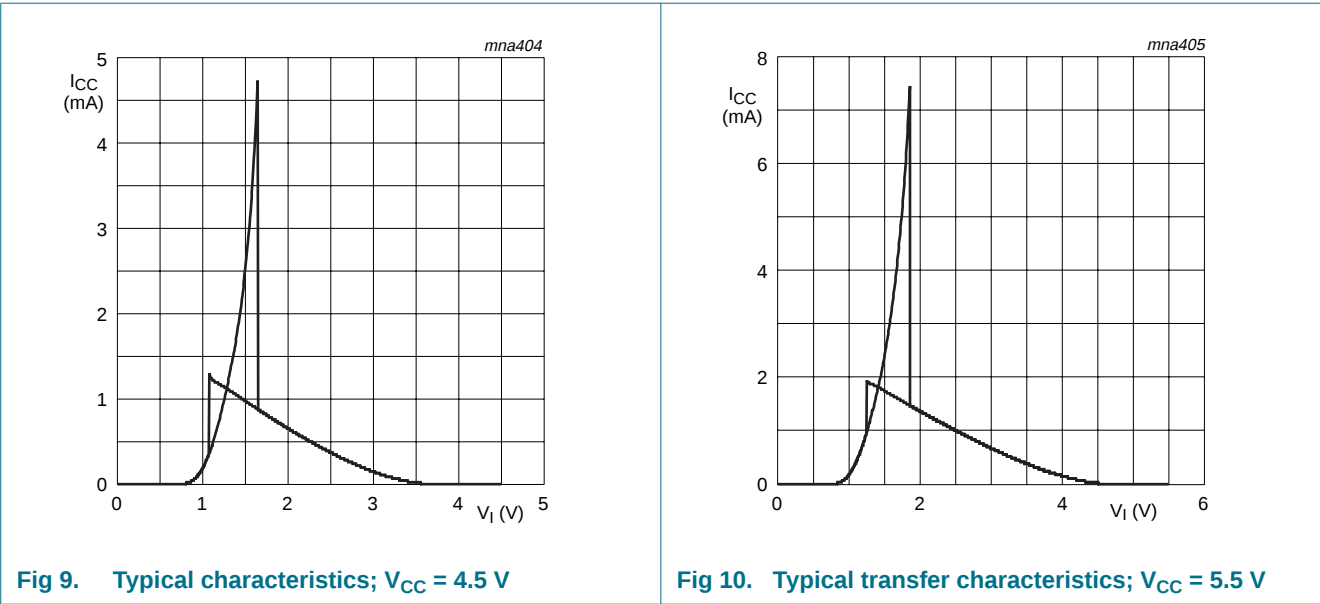
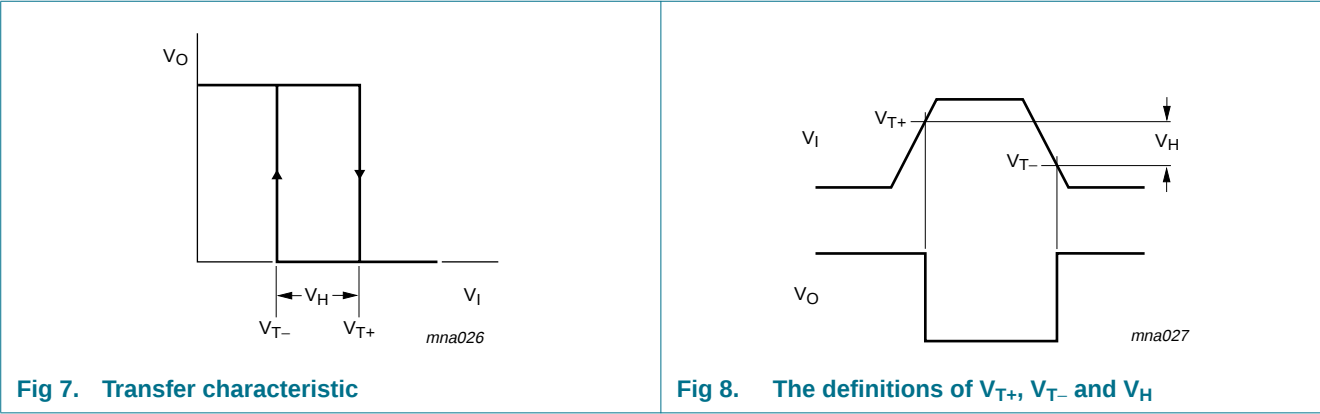


Table 11. Test data

Type	Input		Load	Test
	VI	tr, tf	CL	
XC7SET14	3.0 V	≤ 3.0 ns	15 pF, 50 pF	tPLH, tPHL

13.1 Transfer characteristic waveforms



14. Application information

The slow input rise and fall times cause additional power dissipation, which can be calculated using the following formula:

$$P_{\text{add}} = f_i \times (t_r \times \Delta I_{\text{CC(AV)}} + t_f \times \Delta I_{\text{CC(AV)}}) \times V_{\text{CC}} \text{ where:}$$

P_{add} = additional power dissipation (μW);

f_i = input frequency (MHz);

t_r = input rise time (ns); 10 % to 90 %;

t_f = input fall time (ns); 90 % to 10 %;

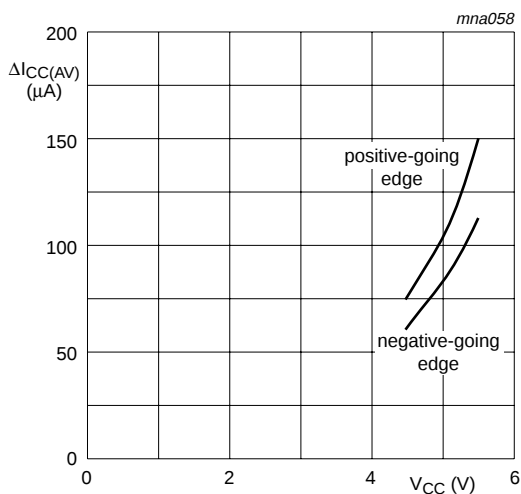
$\Delta I_{\text{CC(AV)}}$ = average additional supply current (μA).

Average additional I_{CC} differs with positive or negative input transitions, as shown in [Figure 11](#).

For XC7SET14 used in relaxation oscillator circuit, see [Figure 12](#).

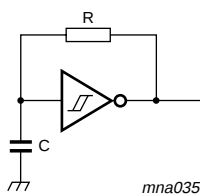
Note to the application information:

1. All values given are typical unless otherwise specified.



Linear change of V_i between $0.1V_{\text{CC}}$ to $0.9V_{\text{CC}}$

Fig 11. Average additional I_{CC}



$$f = \frac{1}{T} \approx \frac{1}{0.60 \times RC}$$

Fig 12. Relaxation oscillator using the XC7SET14

15. Package outline

TSSOP5: plastic thin shrink small outline package; 5 leads; body width 1.25 mmSOT353-1

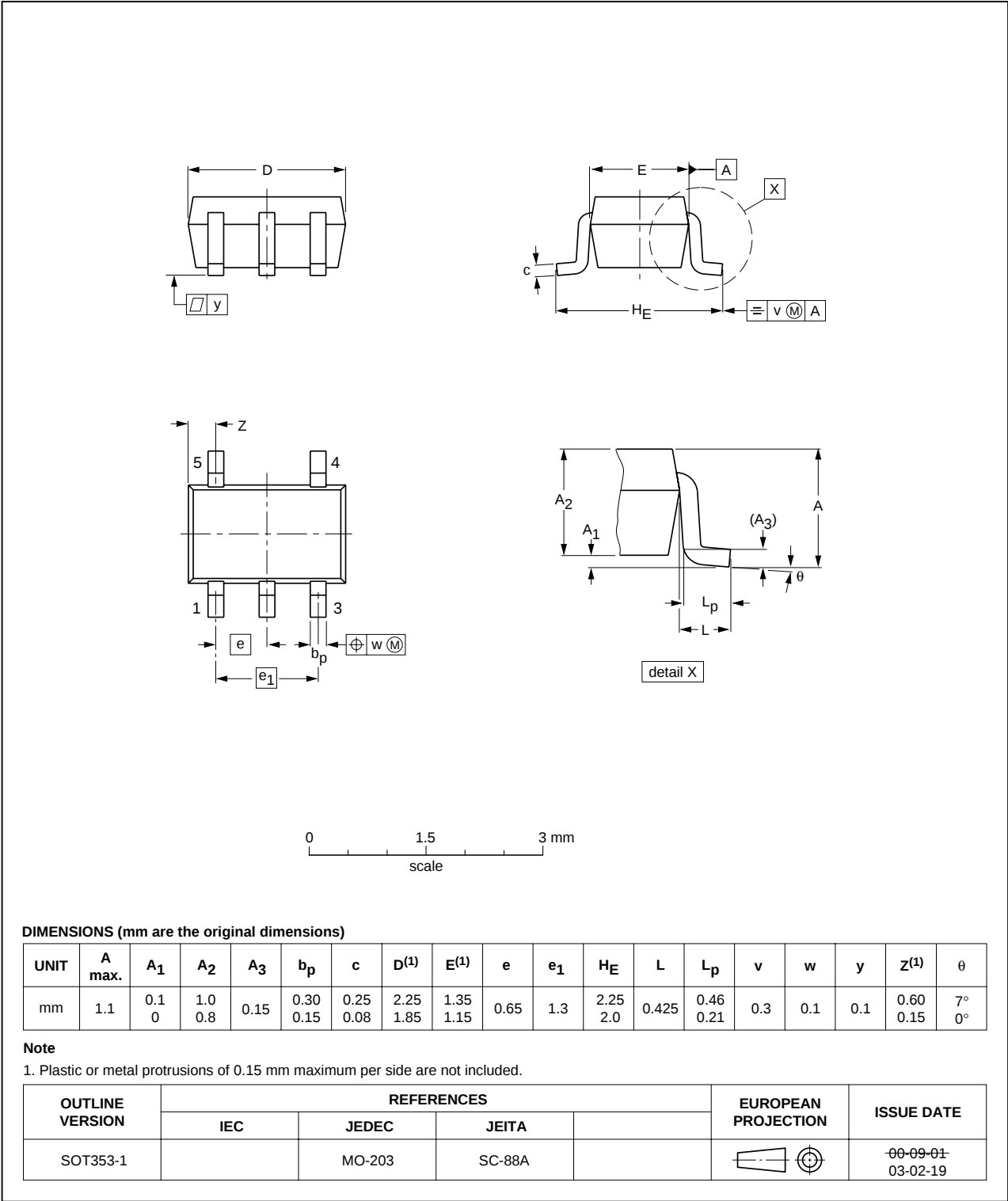


Fig 13. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

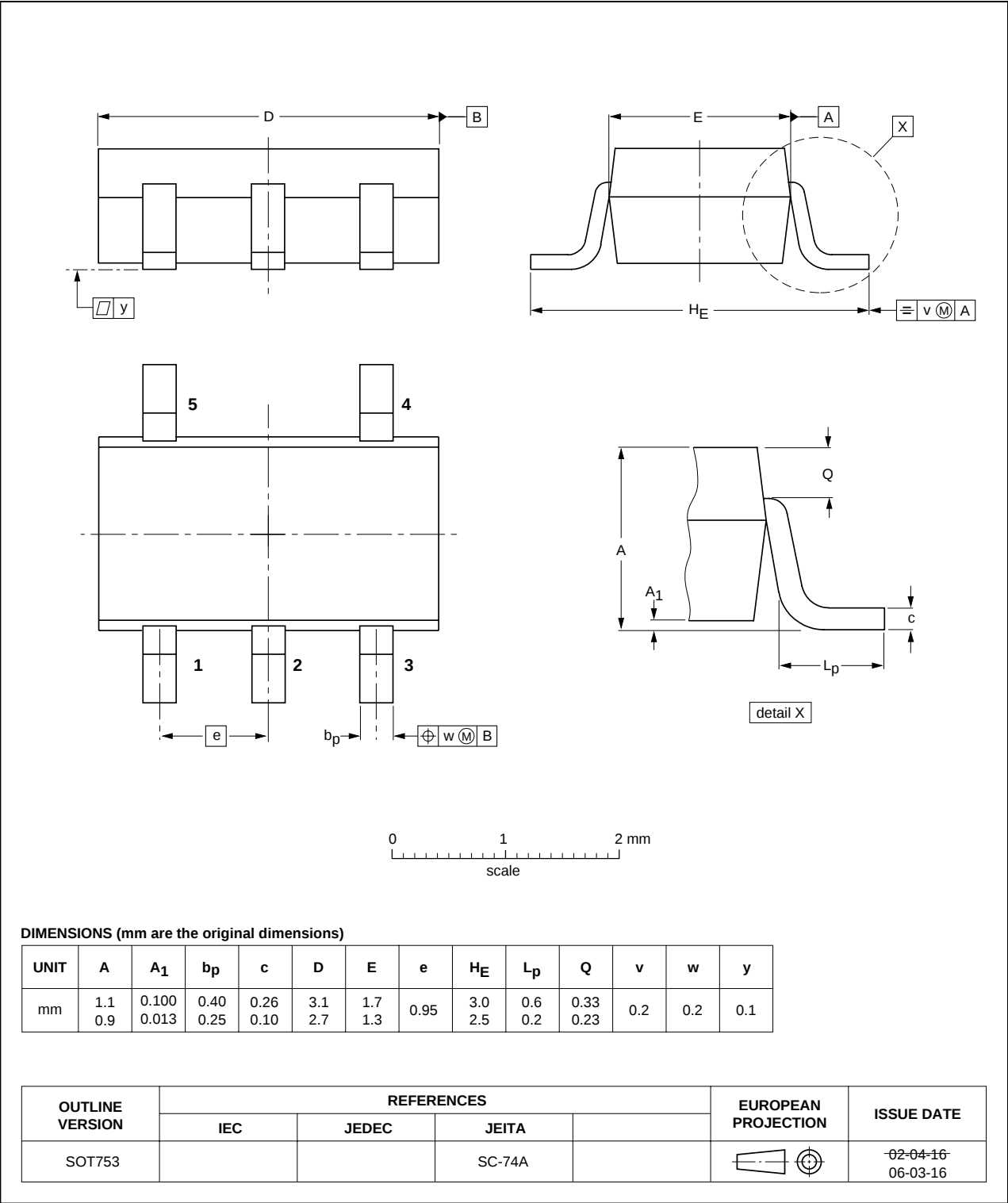


Fig 14. Package outline SOT753 (SC-74A)

16. Abbreviations

Table 12. Abbreviations

Acronym	Description
CDM	Charged Device Model
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model

17. Revision history

Table 13. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
XC7SET14_1	20090831	Product data sheet	-	-

18. Legal information

18.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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[2] The term 'short data sheet' is explained in section "Definitions".

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